

MATERIAL DECLARATION SHEET



Material Number	SMCJ Series		
Product Line	ESD Protection Products		
Compliance Date	1 Jan 2005		
RoHS Compliant	Yes	MSL	1



No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Dice	Silica compound	0.0104	Silicon	7440-21-3	96.5%	4.78%	5%
				Lead oxide	1317-36-8	2.5%	0.124%	
				Nickel	7440-02-0	1%	0.05%	
2	Solder Paste	High-melting point solder	0.0042	Lead	7439-92-1	92.5%	1.85%	2%
				Tin	7440-31-5	5%	0.10%	
				Silver	7440-22-4	2.5%	0.05%	
3	Lead frame & clip	Copper alloy	0.0883	Copper	7440-50-8	99.95%	42.027%	42%
				Zinc	7440-66-6	0.004%	0.002%	
				Iron	7439-89-6	0.01%	0.004%	
				Phosphorus	7723-14-0	0.034%	0.014%	
4	Epoxy material	Epoxy molding compound	0.105	Silica (SiO ₂)	14808-60-7	70%	35%	50%
				Polymer with 1-chloro-2,3-epoxypropane and formaldehyde	29690-82-2	15%	7.5%	
				Phenol-formaldehyde polymer	9003-35-4	10%	5%	
				Antimony trioxide	1309-64-4	2.5%	1.25%	
				TBBA-epichlorohydrin oligomer	40039-93-8	2.5%	1.25%	
5	Plating cover	Matte tin plating	0.0021	Tin	7440-31-5	100%	1	1%
		Total weight	0.2100					

This Document was updated on: 2010-5-18 **Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemptions: 5 – Lead in glass of electronic components; 7a – lead in high melting temperature solders